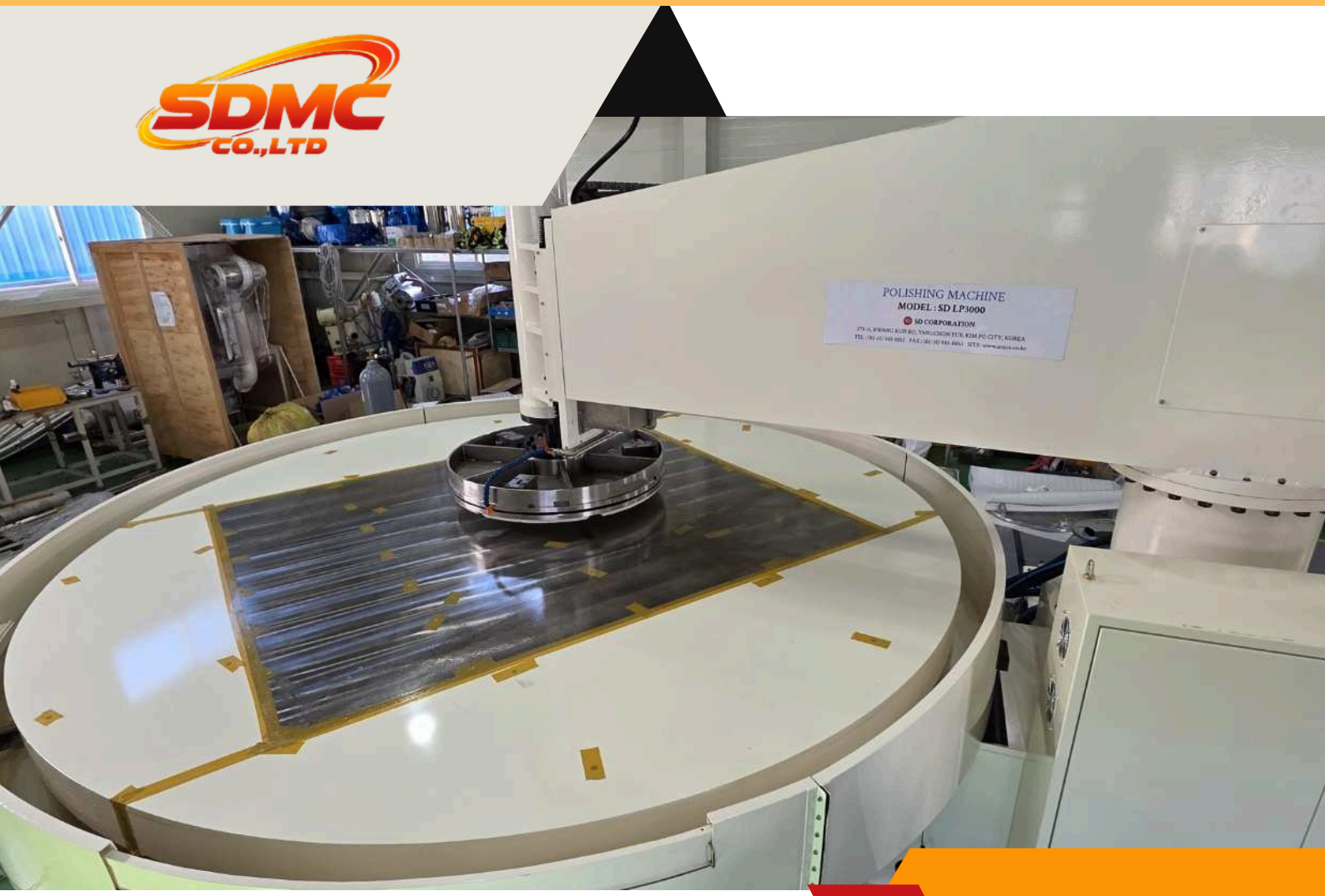
COMPANY PROFILE

Precision Engineering & Manufacturing

SDMC CO.,LTD



website
www.sdmcvn.com

call us
+84 368 000 563

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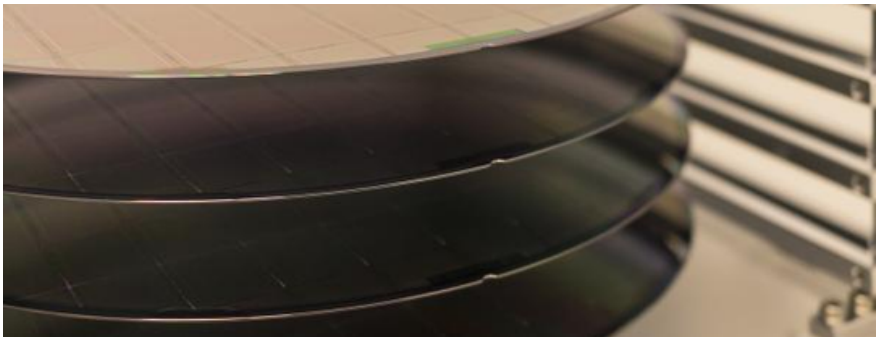
ABOUT US

WHO WE ARE?

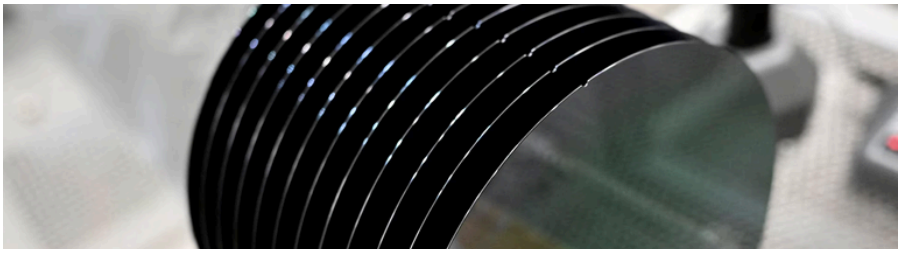
A Professional Manufacturer of Precision Processing Equipment
Founded in 2004, SDMC specializes in the design, manufacturing, and supply of precision lapping and polishing equipment for a wide range of materials, including semiconductor wafers, quartz, ceramics, and glass.
Backed by over 20 years of hands-on engineering experience, we carefully analyze each customer's manufacturing process to provide optimized, customized equipment that minimizes trial and error while maximizing productivity and quality. Beyond equipment manufacturing, SDMC delivers comprehensive solutions—from consultation and installation to stable operation and long-term technical support.

CORE VALUES









Field-Proven Engineering Expertise

With more than 20 years of practical experience in machining semiconductors, ceramics, quartz, glass, and other advanced materials, we develop equipment that is proven in real production environments—not just in theory.

Precision & Quality Assurance

Every machine undergoes rigorous quality inspection and precision verification before delivery, ensuring reliable performance and immediate integration into the customer's production line.

Customized Process Solutions

We provide tailored equipment solutions based on each customer's process requirements, material characteristics, and production capacity. From equipment selection and installation to process optimization and after-sales support, SDMC is committed to your long-term success.

20+
years of Experience
Field-proven engineering expertise

50+
Developed & Delivered Solutions

3,600 MM
Maximum Processing Capacity. One of Korea's largest precision OSCAR polishing machines for ultra-large workpieces.

13 B
Advanced Semiconductor Solutions
Proven experience in supplying equipment for 13B and 16B semiconductor manufacturing processes.



MAJOR PROJECTS & TECHNOLOGY MILESTONES

2025 – Present
Delivered a 3,600 mm Large-Scale OSCAR Polishing Machine.
Delivered a Ø900 mm Precision Single-Side Lapping Machine.
Delivered a Ø900 mm Polishing Machine.
Delivered an Automatic Valve Polishing Machine.
Delivered an Automatic CNC Valve Machining Machine.
Delivered an Advanced 13B Semiconductor Lapping Machine.

2024
Delivered Advanced 13B/16B Semiconductor Polishing Machines.
Delivered an Automatic Ceramic Cutting Machine.
Delivered a Wire Cutting Machine.
Delivered an Automatic Wafer Back Grinding Machine.

2022 – 2023
Delivered an Automatic Polishing Machine for 3D Printed Components.
Delivered an Automatic Ø1,000 mm Ceramic Polishing Machine.
Delivered an Automatic Glass Polishing Machine.
Delivered a 13B Semiconductor Shower Head Polishing Machine.

2020 – 2021
Delivered a 2,500 mm OLED Substrate Polishing Machine.
Developed Lapping & Polishing Technology for Semiconductor Aluminum Materials.
Acquired proprietary Aluminum Polishing Technology and machining equipment.
Successfully modified and delivered a Diamond Plate Lapping & Grinding Machine.

2018 – 2019
Delivered a 500 mm 4-Axis OSCAR Grinding Machine.
Delivered a Stainless Steel Polishing Plate Grinding Machine.
Delivered a Lapping Machine for Ultrasonic Components.

2016 – 2017
Delivered a Double-Side Diamond Plate Lapping Machine.
Delivered a Precision Single-Side Lapping Machine for Automotive Brake Discs.

2014 – 2015
Delivered a 5-Axis Automatic CNC Glass Cutting Machine for automotive parts manufacturers.
Delivered a Ø930 mm Ceramic Ring Lapping Machine.
Delivered a Ceramic Polishing Machine.

2012 – 2013
Successfully developed Lapping & Polishing Technology for Brittle Filter Materials.
Delivered an Advanced Lapping & Polishing Machine to a 16B Semiconductor Manufacturer.
Delivered a CNC Glass Cutting Machine.
Delivered an Automatic Ceramic Grinding Machine for mobile phone components.

2010 – 2011
Delivered an Automatic Glass Edge Chamfering Machine.
Developed an Automatic Multi-Blade Cutting Machine with grinding amount calculation.
Developed a Glass Edge Chamfering Machine for mobile phones.
Developed a Glass Polishing Machine for mobile phones.

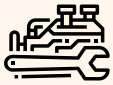
2008 – 2009
Delivered a Ceramic Lapping Machine.
Delivered a Stainless Steel Polishing Machine.
Delivered an Automatic Terminal Tapping Machine for mobile phones.

2006 – 2007
Developed an Automatic Horizontal Polishing Machine with Diamond Wheel.
Exported an Automatic Quartz Crystal Resonator Assembly Machine to China.

2004
Founded SDMC Co., Ltd.
Delivered two (2) sets of 18B Double-Side Lapping Machines to a semiconductor wafer manufacturer.

PRODUCTS AND SOLUTIONS

SDMC supply precision lapping and polishing machines, semiconductor processing equipments, consumables, and technical solutions



MACHINES

High-precision lapping, polishing, grinding, cutting, and inspection equipment designed for semiconductor and advanced material processing.



CONSUMABLES

Premium polishing pads, slurry, diamond plates, abrasives, and other consumables to maximize machining performance and product quality.



TECHNICAL SOLUTIONS

Complete engineering support, including process optimization, equipment selection, installation, training, and after-sales technical service.

SINGLE SIDE LAPPING M/C

LAPPING & POLISHING MACHINE (600,900,1000MM)

Specification	SDLP600, 900, 1000
Machine Dimensions	Width 1370mm I Length 1300mm
Motor Specifications	Table Plate 5-15HP / 208-240V or 420-480V (3-phase)
Plate Diameter	400, 600, 900, 1000 mm
Product Diameter	200, 300, 400, 450 mm
Control System	Mitsubishi color touch screen, PLC SYSTEM
Automatic Thickness Control	Avaiable
Ring (ceramic ring)	SPEED Change availiable by forced motor Ensures high stability and precision.
Plate Material	High-quality stainless steel
Other option Features	Plate weight control, extended warranty and training support



SINGLE SIDE LAPPING M/C

LAPPING & POLISHING MACHINE (600,900,1000MM) (TYPE B)

Specification	SDLP600, 900, 1000
Machine Dimensions	Width 1370mm I Length 1300mm
Motor Specifications	Table Plate 5-15HP / 208-240V or 420-480V (3-phase)
Plate Diameter	400, 600, 900, 1000 mm
Product Diameter	200, 300, 400, 450 mm
Control System	Mitsubishi color touch screen, PLC SYSTEM
Automatic Thickness Control	Avaiable
Ring (ceramic ring)	SPEED Change availiable by forced motor Ensures high stability and precision.
Plate Material	High-quality stainless steel
Other option Features	Plate weight control, extended warranty and training support



DOUBLE SIDE LAPPING M/C

DOUBLE SIDE LAPPING & POLISHING MACHINE 20B-5L

Model	SDLP1300
Machine Dimensions	Width 1370mm I Length 2130mm I Height 2500mm
Approx. Weight	2500 kg
Motor Specifications	Upper plate: 15HP / Table Plate: 15 / Sungear: 3HP
Voltage	208-240V or 420-480V (3-phase)
Plate Diameter	1384 mm
Carrier Diameter	508.0 mm (5 carriers)
Control System	Mitsubishi color touch screen, PLC SYSTEM
Automatic Thickness Control	Attached
Center/Ring Gear	Stainless steel, SPEED Change available
Other Options	ATC, optional LOAD CELL, upper plate weight control, extended warranty



DOUBLE SIDE LAPPING M/C

DOUBLE SIDE LAPPING & POLISHING MACHINE 3,4,6,9,13,16,20,22B-5L

Model	SDLP-3,4,6,9,13,16,20,22B
Machine Dimensions	600×800 ~ 1350×1800 (manufactured according to carrier size)
Motor Specifications	Upper plate: 2-20HP / Table Plate: 1-20 / Sungear: 0.4-3HP
Voltage	208-240V or 420-480V (3-phase)
Plate Diameter	200mm ~ 1400 mm
Carrier Diameter	3inch ~ 22inch (5 carriers)
Control System	Mitsubishi color touch screen, PLC SYSTEM
Automatic Thickness Control	Attached
Center/Ring Gear	Stainless steel, SPEED Change available, high stability
Other Options	ATC, optional LOAD CELL, upper plate weight control, extended warranty



AUTOMATIC SYSTEM

QUARTZ ANGLE MEASUREMENT SYSTEM

Operation	Fully Automatic (Automatic Feeder Inserting System)
Measurement Method	Automatic X-ray beam projection → Computerized peak analysis → Automatic classification by cutting angle
Application	Quartz units for military, satellite, and missile industries
Analysis System	High-Voltage X-ray Analysis System
Key Feature	Korea's first fully automatic optical quartz classification system



AUTOMATIC SYSTEM

MULTI WIRE CUTTING MACHINE

Operation	Full Automatic, Diamond cutting with rocking unit
Max work size	270(L) × 150(W) × 150(H) mm
Wire reciprocation speed	Max. 700m/min
Main shaft swing angle	0 ~ ±5°
Work table elevation stroke	220mm
Slicing speed	0.1 ~ 2.5mm/min
Roller diameter	155 ~ 135mm
Air supply/consumption	0.5MPa / 800L/min
Machine dimensions	1900 × 2000 × 2600 mm
Machine net weight	Approx. 6000 KG



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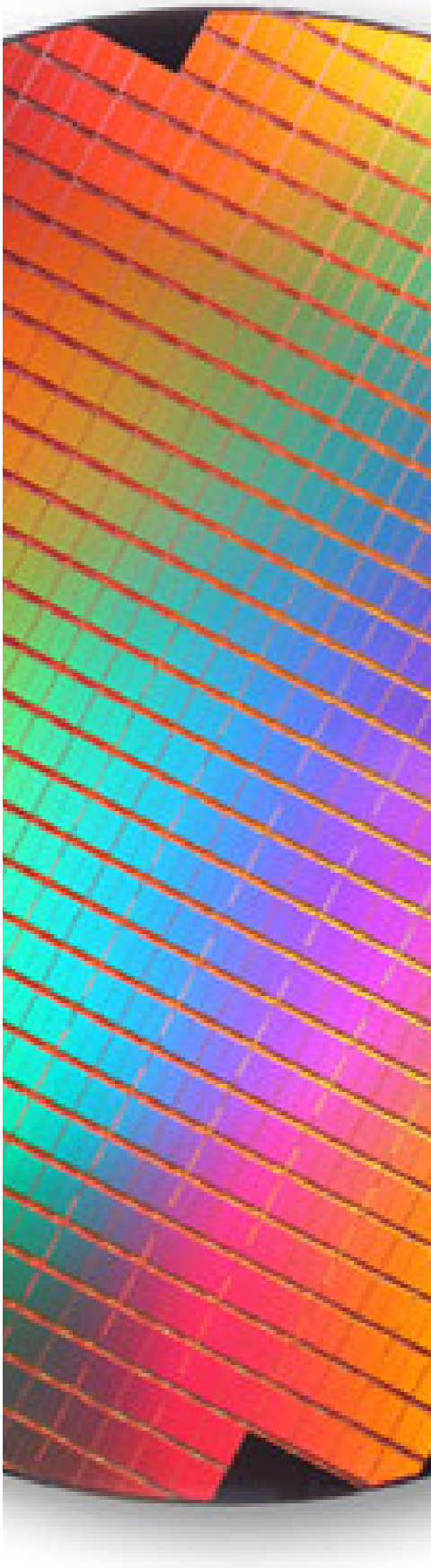

HEAD OFFICE

ADDRESS

60, Hwanggeum-ro 257beon-gil,
Yangchon-eup, Gimpo-si, Gyeonggi-do,
Republic of Korea

CONTACT

Tel. +82-31-982-8871
Fax. +82-31-982-8872

BUSINESS HOURS

Weekdays 09:00 – 18:00

SDMC CO., LTD

GET IN TOUCH!

aexon@hanmail.net